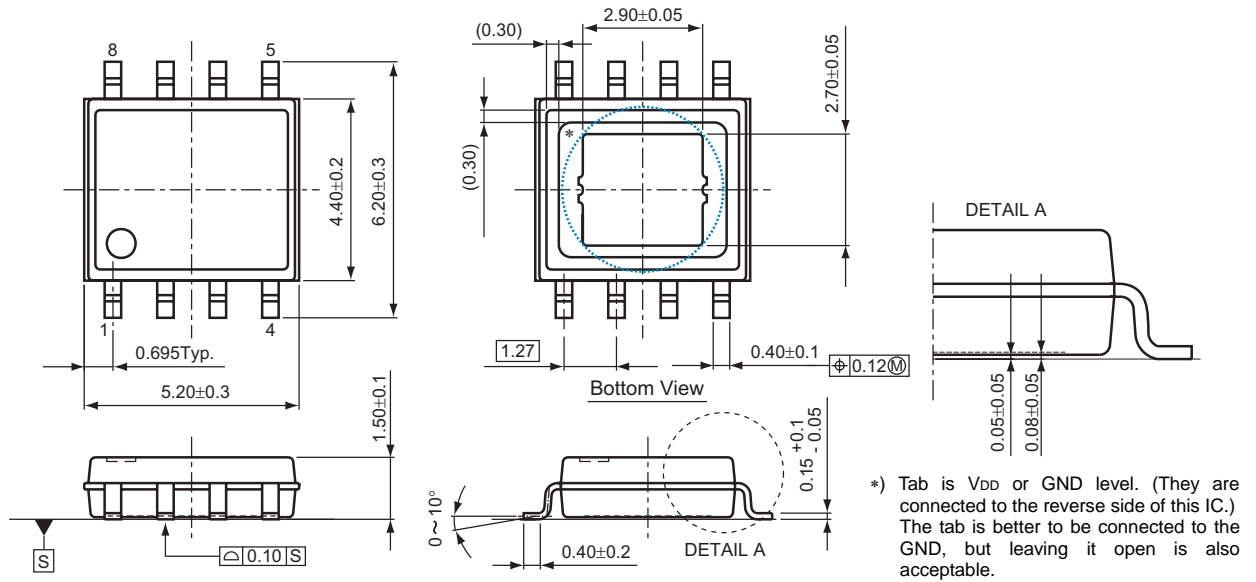


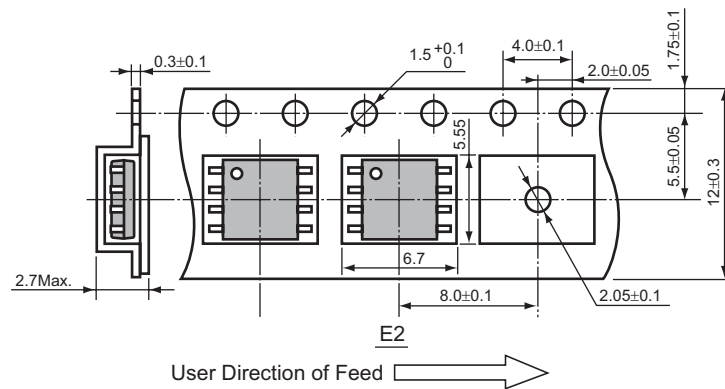
• HSOP-8E

Unit: mm

PACKAGE DIMENSIONS

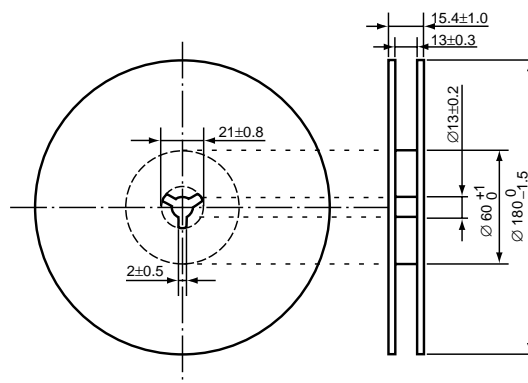


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-12Bc)

(1reel=1,000pcs)



POWER DISSIPATION (HSOP-8E)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

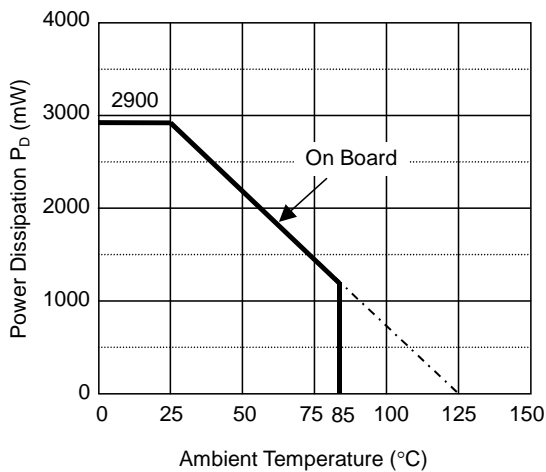
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (4 layers)
Board Dimensions	76.2mm × 114.3mm × 0.8mm
Copper Ratio	Top side, Back side : 50mm square : Approx.95% 2nd, 3rd : : 50mm square : 100%
Through-holes	φ0.4mm × 21pcs

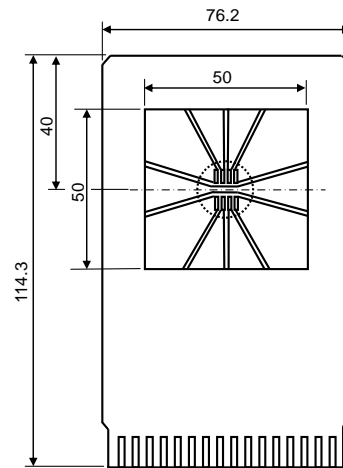
Measurement Results

($T_{opt}=25^{\circ}C$, $T_{jmax}=125^{\circ}C$)

	Standard Land Pattern
Power Dissipation	2900mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/2.9W=35^{\circ}C/W$
Thermal Resistance	$\theta_{jc}=10^{\circ}C/W$



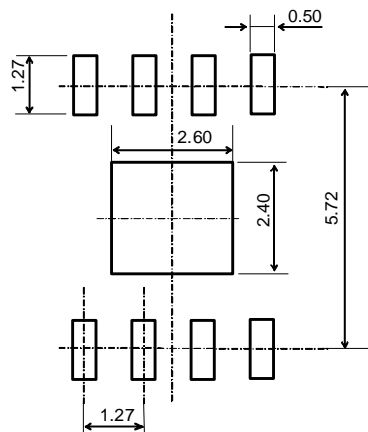
Power Dissipation



Measurement Board Pattern

○ IC Mount Area (Unit: mm)

RECOMMENDED LAND PATTERN



(Unit: mm)